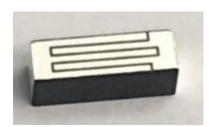




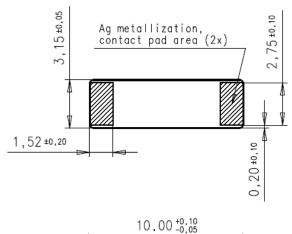
Series: Ceramic Antenna

PART NUMBER: W3015L



Features:

- SMT Chip Antenna
- 433MHz
- 10x3.2x4mm
- MSL-1



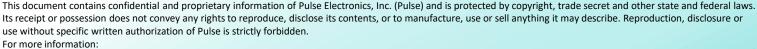
Applications:

- ISM radios for 433MHz
- Remote controls
- IoT, M2M

All dimensions are in mm / inches

Issue: 2035

In the effort to improve our products, we reserve the right to make changes judged to be necessary. $\texttt{CONFIDENTIAL} \ \texttt{AND} \ \texttt{PROPRIETARY} \ \texttt{INFORMATION}$



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Series: Ceramic Antenna

PART NUMBER: W3015L

ELECTRICAL SPECIFICATIONS

Frequency 433MHz

Nominal Impedance 50Ω

VSWR <2

Gain 0dBi +/- 1 dB

Efficiency(%) 45%

Polarization Linear

Power withstanding 3W

TECHNICAL DATA SHEET



Description: ISM433MHz Embedded Antenna

Series: Ceramic Antenna

PART NUMBER: W3015L

MECHANICAL SPECIFICATIONS

Weight 0.64g

Size $(W \times L \times H)$ 10x3.2x4mm

MSL (Moisture Sensitivity Level) 1

ENVIRONMENTAL SPECIFICATIONS

Operating temperature $-40\sim +85^{\circ}$ C

Storage temperature $-10\sim +30^{\circ}$ C

Humidity Cyclic 6 +25° C/+55° C 95%

Vibration

Sinusoidal 2-8Hz 7.5 mm

Sinusoidal 8-200Hz 20 m/s²

Shocks 0.5 m/s

Salt mist 96 hours

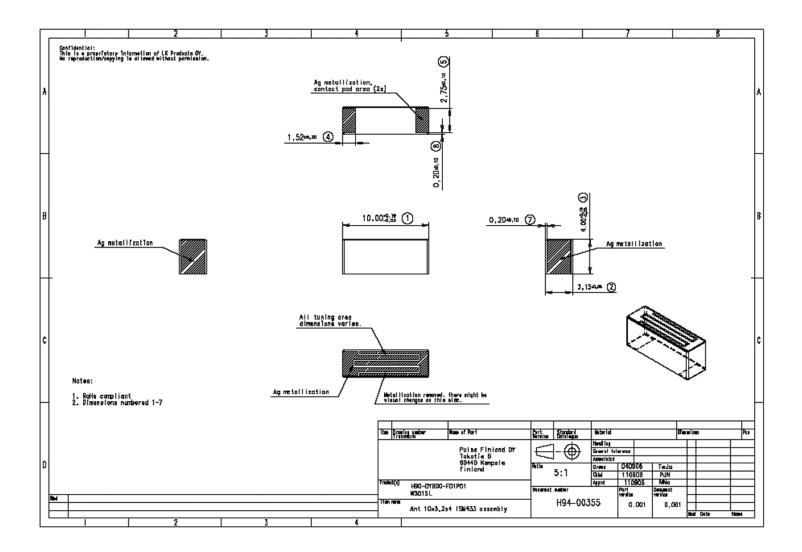




Series: Ceramic Antenna

PART NUMBER: W3015L

MECHANICAL DRAWING









Series: Ceramic Antenna

PART NUMBER: W3015L

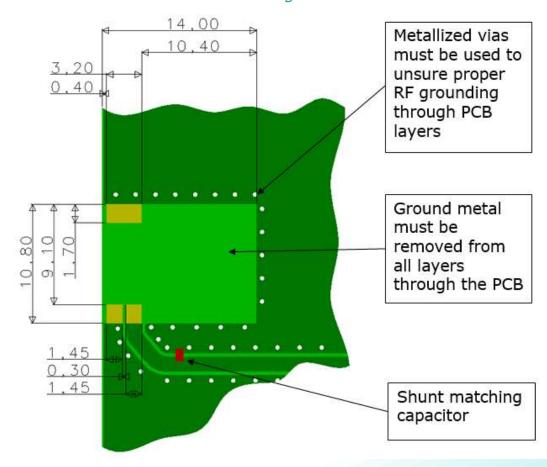
MECHANICAL DRAWING

ISM 433 MHz Antenna

Ceramic Chip Antenna (ground cleared under antenna 10.80 mm x 14.00 mm)

Recommended test board for electrical characteristic measurement:

- Ground clearance area dimensions
- Soldering pad layout
- External matching component
 - 33pF 0402 sized parallel shunt capacitor, exact capacitor value depends on used board and feed line configuration



Issue: 2035

ROHS

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION



Series: Ceramic Antenna

PART NUMBER: W3015L

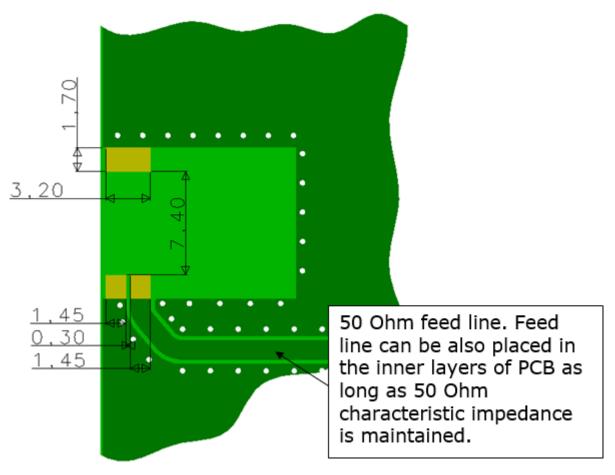
MECHANICAL DRAWING

ISM 433 MHz Antenna

Ceramic Chip Antenna (ground cleared under antenna 10.80 mm x 14.00 mm)

Recommended test board for electrical characteristic measurement:

- Detailed soldering pad dimensions
 - Note: Antenna chip has only two soldering terminals (see figure 1.) but in PCB the feed pad is separated from the adjacent ground pad due to impedance matching









Series: Ceramic Antenna

PART NUMBER: W3015L

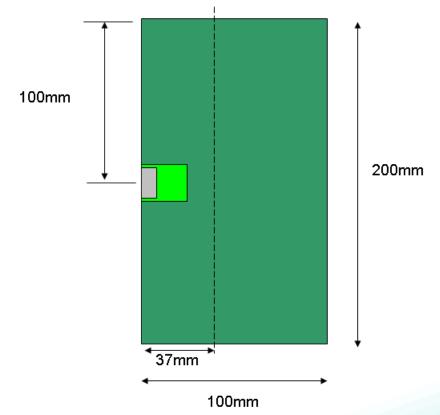
MECHANICAL DRAWING

ISM 433 MHz Antenna

Ceramic Chip Antenna (ground cleared under antenna 10.80 mm x 14.00 mm)

Recommended test board for electrical characteristic measurement:

- Evaluation board outline dimensions
 - o 200 x 100 mm or 200 x 37 mm (note difference in performance, see table 1.)
- Antenna placement on evaluation board
 - In the centre of the board long (200 mm) edge



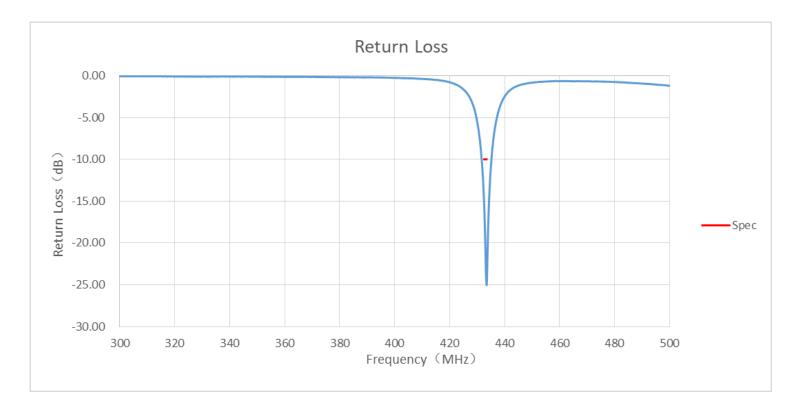




Series: Ceramic Antenna

PART NUMBER: W3015L

CHARTS



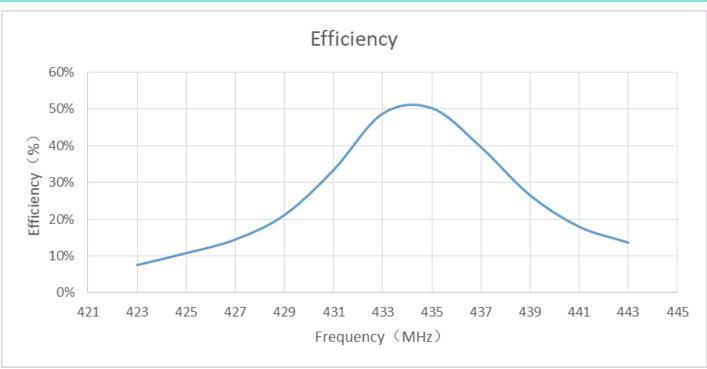


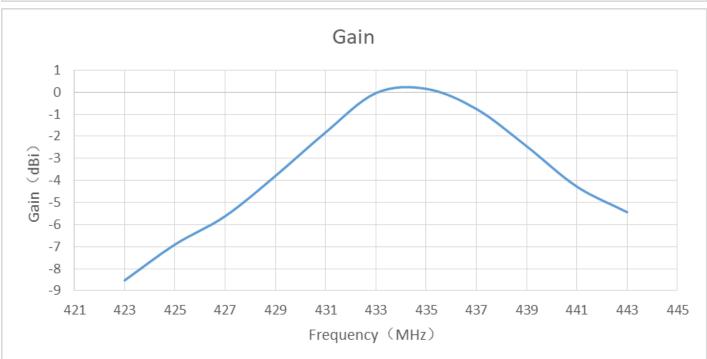


Series: Ceramic Antenna

PART NUMBER: W3015L

CHARTS





Issue: 2035

RóHS

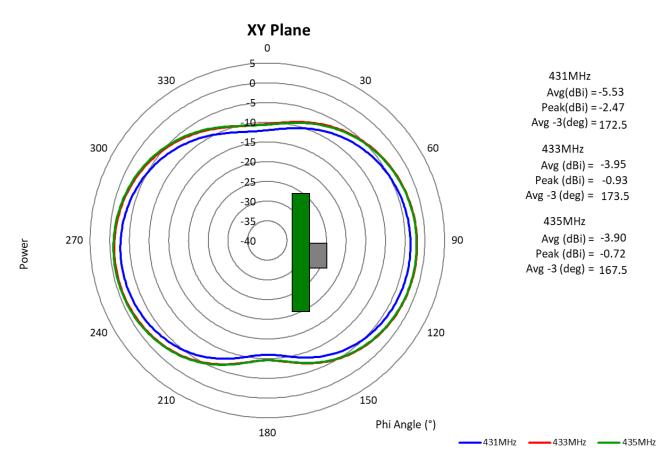


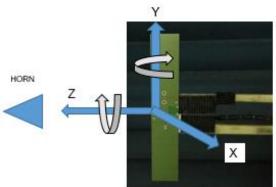
Series: Ceramic Antenna

PART NUMBER: W3015L

CHARTS

Typical free space radiation pattern









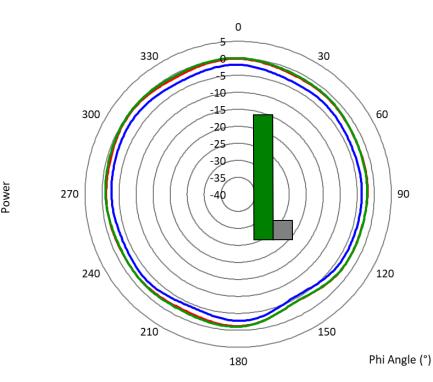
Series: Ceramic Antenna

PART NUMBER: W3015L

CHARTS

Typical free space radiation pattern

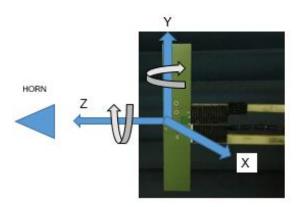
XZ Plane



Avg -3(deg) = 339.5 433MHz Avg (dBi) = -1.55 Peak (dBi) = -0.08 Avg -3 (deg) = 333.5 435MHz Avg (dBi) = -1.38 Peak (dBi) = 0.13 Avg -3 (deg) = 328.5

431MHz Avg(dBi) = -3.20

Peak(dBi) = -1.88



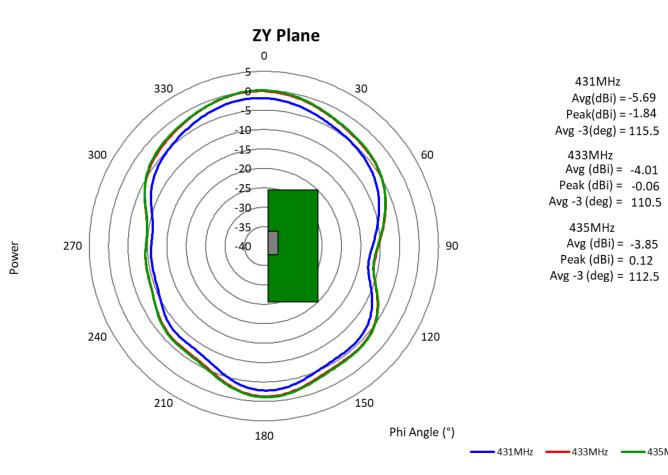


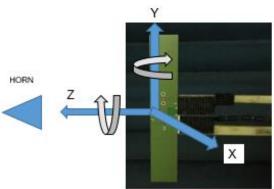
Series: Ceramic Antenna

PART NUMBER: W3015L

CHARTS

Typical free space radiation pattern







Series: Ceramic Antenna

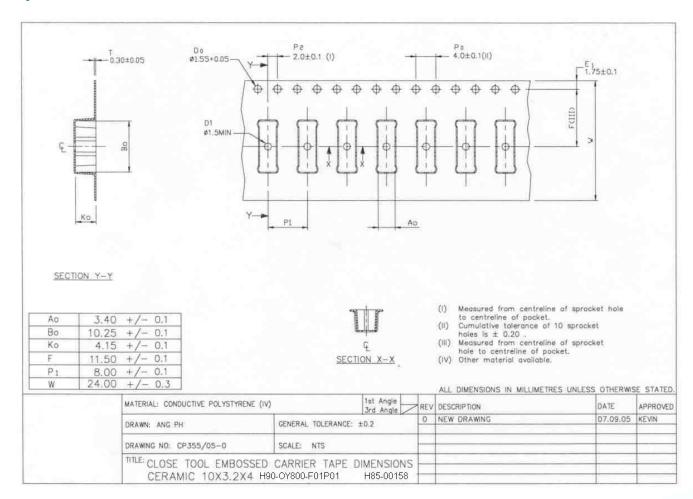
PART NUMBER: W3015L

PACKAGING

General

Tape and reel packing is used. Carrier tape, reel and box dimensions are presented in following pictures.

Carrier Tape







Series: Ceramic Antenna

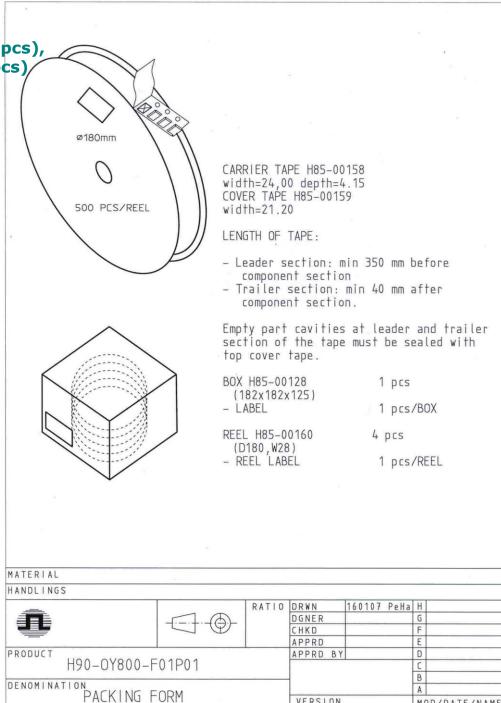
PART NUMBER: W3015L

Packing form

500pcs in one Reel,

3 reel in one inbox (1500 pcs),

2 inbox in out box (3000pcs)



Issue: 2035

MOD/DATE/NAME

VERSION

TECHNICAL DATA SHEET



Description: ISM433MHz Embedded Antenna

Series: Ceramic Antenna

PART NUMBER: W3015L

Recommendations for ceramic chip antenna storage

Storage time

Products should be used within 6 months from the day of manufacturers packaging even when they are stored under below mentioned conditions. Longer storage period may decrease the component solderability.

Storage environmental conditions

To maintain solderability of Pulse ceramic products care must be taken to control the storage and use conditions:

- Do not store or use products in a corrosive atmosphere, especially where chloride, sulphur or sulfide, alkali or acid salts exist in the air. Corrosive gases may cause oxidation of electrodes and reduce solderability
- Keep temperature and humidity stabile and do not exceed the below mentioned minimum and maximum conditions: Temperature: -10 to +30 Deg C Humidity: below 60% RH
- Do not store the products under direct sun light.

It is recommended to keep the products in manufacturers packing (tape&reel) until the time of assembly and soldering process. Air tight vacuum package is recommended in the conditions where it is know to be some corrosive gases.

Handling

Do not touch the components with bare hands. Protective gloves must be used to prevent contamination of terminals which may cause reduced solderability. Do not touch or damage the silver plated surface by any sharp objects. Soft materials (plastic, wood etc.) must be used if tweezers or other tools are used to pick the components. Avoid any excess mechanical shock or vibration during storage and handling.



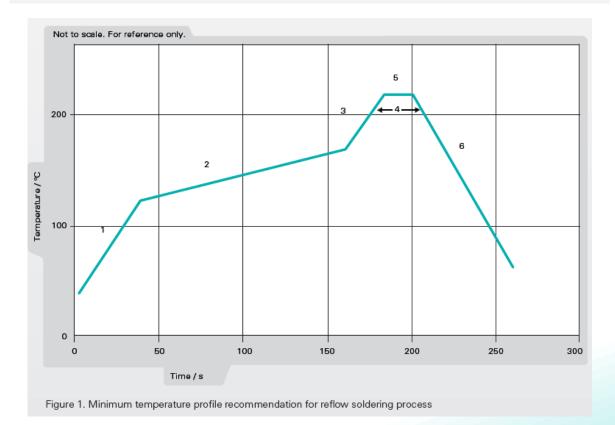
Series: Ceramic Antenna

PART NUMBER: W3015L

Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s





Series: Ceramic Antenna

PART NUMBER: W3015L

Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

